



CAPABILITIES

OVERVIEW



	Standard	Advanced
CIRCUIT / PANEL SIZE		
Metal Clad PCB	510 x 610mm, 457 x 610mmm	Larger sizes available for long boards
MATERIALC		
MATERIALS		
Aluminium	Denka, Ventec, Bergquist, Laird, and more	
Other Materials	Please Enquire	
COPPER FOIL		
Metal Clad PCB	107 (2Fum) 407 (140um)	Hongier weights achievable under consultation
Metal Clau PCB	1oz (35μm) – 4oz (140μm)	Heavier weights achievable under consultation
SURFACE FINISHES		
Lead Free Hot Air Solder Level	Yes	Yes
OSP	Yes	Yes
Immersion Gold (ENIG)	Yes	Yes
ENEPIG		Yes
Immersion Silver		Yes
Immersion Tin		Yes
SOLDER MASKS, IDENTS AN Photoimageable (LPI) Solder Mask Peelable Solder Mask	D CARBON Green, White, Black, Red, Blue Standard & Hi-Temp—Blue, Green, Red	Orange, Purple, Grey & Others on request Standard & Hi-Temp—Blue, Green, Red
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UV Curable ident (Silkscreen) Carbon Key Pads	White, Yellow, Black Yes	Green, Red, Blue, Brown Yes
Carbon Links	No	Yes
Calbon Links	NO	les
CNC DRILLING		
Min. Finished Hole Size (Mechanical)	0.60mm x Material Thickness	Smaller considered on a case by case basis
Max. Finished Hole Size (Mechanical)	5.90mm	Holes over 5.90mm diameter are routed
Minimum Punched Hole Size	1.00mm x Material Thickness	
Minimum Router Diameter	1.6mm 1.6mm	
TRACK WIDTH		
THE CONTROL OF THE CO	Copper Thickness	Minimum Width
	1oz (35um)	0.005" (0.13mm)
	2oz (70um)	0.006" (0.15mm)
	3oz (105um)	0.007" (0.18mm)
	4oz (140um)	0.008" (0.20mm)
	6oz (210um)	0.010" (0.25mm)
	8oz (280um)	0.015" (0.38mm)
	10oz (350um)	0.015" (0.38mm)



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TRACK GAP

Copper Thickness	Minimum Width
1oz (35um)	0.007" (0.18mm)
2oz (70um)	0.009" (0.23mm)
3oz (105um)	0.012" (0.30mm)
4oz (140um)	0.014" (0.36mm)
6oz (210um)	0.020" (0.51mm)
8oz (280um)	0.024" (0.61mm)
10oz (350um)	0.030" (0.76mm)

MINIMUM TRACK TO PROFILE

	Standard	
Scored	0.50mm	
Routed	0.40mm	
Punched	One material thickness	

SOLDER RESIST

	Standard	
Soldermask	The solder resist clearance around copper pads should be 0.1mm – this can be reduced to	
	0.05mm to maintain a 0.20mm solder dam	
Solder Dam Width	Min 0.20mm	
Solder Mask Pad Size	Min 0.30mm x 0.30mm	
Character Height (Text In Resist)	For the purposes of legible text, a minimum character height of 0.2mm is recommended	

IDENT

	Standard
Minimum Character Height	1.20mm
Minimum Character Width	0.25mm
Minimum Text Line Thickness	0.25mm
Ident Text and Line to Copper Pad	0.20mm – No ident text or lines to encroach onto copper pads
Minimum Distance to Board Profile	0.50mm

DRILLING & PUNCHING

	Drilled	Routed
Minimum Hole Edge to Circuit Pro	ofile 1.0mm	One material thickness
Minimum Hole to Hole Edge	1.0mm	One material thickness

ELECTRICAL TEST

	Standard	Advanced
% Tested (Open / Short test)	100%	100%
Hi-Pot Breakdown Test	On Request	On Request



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LEAD TIMES: UK MANUFACTURE

Standard	Quick Turn
10-15 Days	3-5 Days

LEAD TIMES: FAR EAST MANUFACTURE

Standard	Quick Turn
10-15 Days + Shipping	10 Days + Shipping

Air Freight Lead Time – 5 Days

Sea Freight Lead Time – 20 Days

All Far East lead times are subject to customs clearance

Premium International shipments can be arranged by DHL, Fedex, UPS or TNT at extra cost

